

Automation Probing Solutions

- Fully Automatic Versions
 - Single-Sided or Double-Sided
 - Vacuum
- Die, Frames and Wafers (50 mm to 300 mm)
- Solutions for multiple applications – DC, RF, MEMS, Silicon Photonics, Power and more
- Thermal Systems from -60 C to 300 C
- Pre-Aligners, End-Effectors, Grippers, Bar Code, OCR
- Customized Chucks and Carrier Plates
- Integrating Spheres or Fibers (single or multi-mode)
- Manipulators – manual, programmable and hexapods
- Non-Contact Height Measurement Sensors
- Probe Tips, Probe Cards, Wedges
- Integrated Solutions
- Modular PS4L Hardware & Software Architecture

